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RELIABILITY REPORT

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RELIABILITY DATA LT1113 8/21/2006					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽¹⁾ AT +125°C	NUMBER OF ⁽²⁾ FAILURES
PLASTIC DIP	172 172	9312	9312	1,008.40 1,008.40	0 0
• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICF HOURS ⁽⁴⁾ AT +85°C	NUMBER OF FAILURES
PLASTIC DIP SOIC/SOT/MSOP	50 33 83	9648 9708	9648 9708	336.00 174.24 510.24	0 0 0
• PRESSURE COOKER TEST AT 15 PSIG, +121°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP SOIC/SOT/MSOP	1,100 250 1,350	9338 9337	9926 0041	35.00 6.00 41.00	0 0 0
• TEMP CYCLE FROM -65°C to +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
SOIC/SOT/MSOP	100 100	9942	0041	10.00 10.00	0 0
• THERMAL SHOCK FROM -65°C to +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
SOIC/SOT/MSOP	100 100	9942	0041	10.00 10.00	0
 (1) Assumes Activation Energy = 1.0 Electron Volts (2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 1.82 FITS (3) Mean Time Between Failures in Years = 62,680 (4) Assumes 20X Acceleration from 85°C to +131°C Note: 1 FIT = 1 Failure in One Billion Hours. 					